V2

Application note n° 50

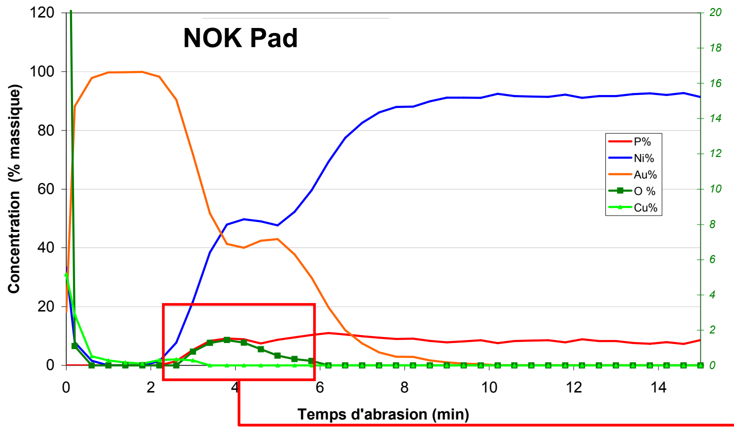
Analysis of a black pad on a PCB

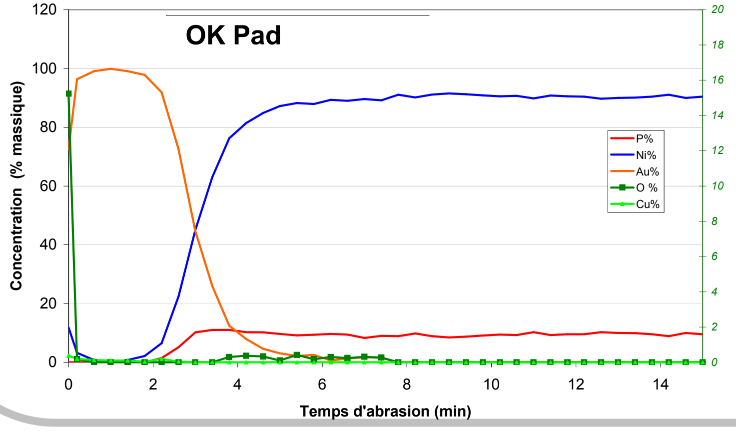
Subject: **origin of a welding defect of components on pads of a PCB**

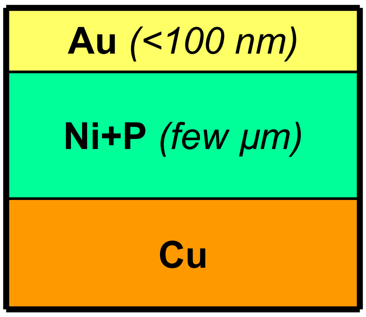
Technique: **XPS**

- ✓ **quantitative depth profiles**
- ✓ **layers depth: from few nm to few µm**

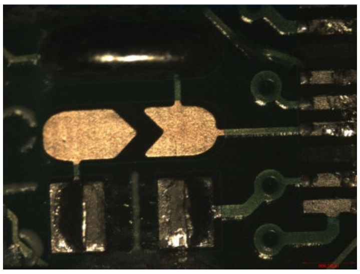
Results:







Oxydation at the interface Au/NiP coating



Layers Cu/NiP/Au

Conclusion:

Welding defect due to an oxydation phenomenon localised at Au /NiP interface